

3.4.1 PRI_IDLE MODE

This mode is unique among the three low-power Idle modes in that it does not disable the primary device clock. For timing sensitive applications, this allows for the fastest resumption of device operation, with its more accurate primary clock source, since the clock source does not have to “warm up” or transition from another oscillator.

PRI_IDLE mode is entered from PRI_RUN mode by setting the IDLEN bit and executing a `SLEEP` instruction. If the device is in another Run mode, set IDLEN first, then clear the SCS bits and execute `SLEEP`. Although the CPU is disabled, the peripherals continue to be clocked from the primary clock source specified by the FOSC3:FOSC0 Configuration bits. The OSTS bit remains set (see Figure 3-7).

When a wake event occurs, the CPU is clocked from the primary clock source. A delay of interval TcSD is required between the wake event and when code execution starts. This is required to allow the CPU to become ready to execute instructions. After the wake-up, the OSTS bit remains set. The IDLEN and SCS bits are not affected by the wake-up (see Figure 3-8).

3.4.2 SEC_IDLE MODE

In SEC_IDLE mode, the CPU is disabled but the peripherals continue to be clocked from the Timer1 oscillator. This mode is entered from SEC_RUN by setting the IDLEN bit and executing a `SLEEP` instruction. If the device is in another Run mode, set IDLEN first, then set SCS1:SCS0 to '01' and execute `SLEEP`. When the clock source is switched to the Timer1 oscillator, the primary oscillator is shut down, the OSTS bit is cleared and the T1RUN bit is set.

When a wake event occurs, the peripherals continue to be clocked from the Timer1 oscillator. After an interval of TcSD following the wake event, the CPU begins executing code being clocked by the Timer1 oscillator. The IDLEN and SCS bits are not affected by the wake-up; the Timer1 oscillator continues to run (see Figure 3-8).

Note: The Timer1 oscillator should already be running prior to entering SEC_IDLE mode. If the T1OSCEN bit is not set when the `SLEEP` instruction is executed, the `SLEEP` instruction will be ignored and entry to SEC_IDLE mode will not occur. If the Timer1 oscillator is enabled but not yet running, peripheral clocks will be delayed until the oscillator has started. In such situations, initial oscillator operation is far from stable and unpredictable operation may result.

FIGURE 3-7: TRANSITION TIMING FOR ENTRY TO IDLE MODE

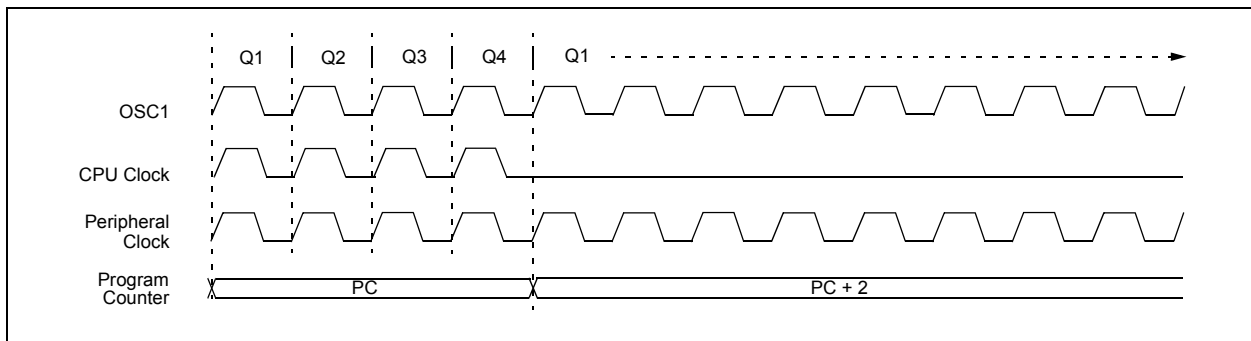
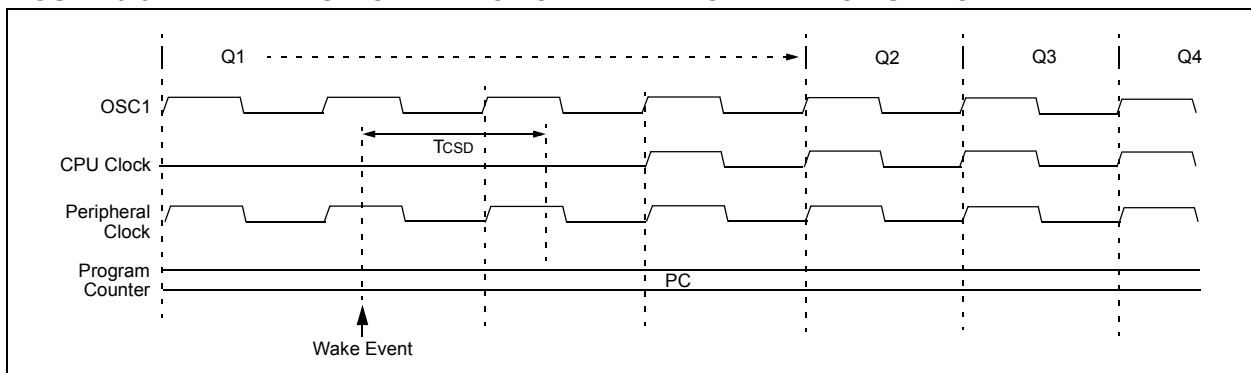


FIGURE 3-8: TRANSITION TIMING FOR WAKE FROM IDLE TO RUN MODE



12.0 TIMER1 MODULE

The Timer1 timer/counter module incorporates these features:

- Software selectable operation as a 16-bit timer or counter
- Readable and writable 8-bit registers (TMR1H and TMR1L)
- Selectable clock source (internal or external) with device clock or Timer1 oscillator internal options
- Interrupt on overflow
- Module Reset on CCP Special Event Trigger
- Device clock status flag (T1RUN)

A simplified block diagram of the Timer1 module is shown in Figure 12-1. A block diagram of the module's operation in Read/Write mode is shown in Figure 12-2.

The module incorporates its own low-power oscillator to provide an additional clocking option. The Timer1 oscillator can also be used as a low-power clock source for the microcontroller in power-managed operation.

Timer1 can also be used to provide Real-Time Clock (RTC) functionality to applications with only a minimal addition of external components and code overhead.

Timer1 is controlled through the T1CON Control register (Register 12-1). It also contains the Timer1 Oscillator Enable bit (T1OSCEN). Timer1 can be enabled or disabled by setting or clearing control bit, TMR1ON (T1CON<0>).

REGISTER 12-1: T1CON: TIMER1 CONTROL REGISTER

R/W-0	R-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
RD16	T1RUN	T1CKPS1	T1CKPS0	T1OSCEN	$\overline{T1SYNC}$	TMR1CS	TMR1ON
bit 7							bit 0

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

- bit 7 **RD16:** 16-Bit Read/Write Mode Enable bit
1 = Enables register read/write of Timer1 in one 16-bit operation
0 = Enables register read/write of Timer1 in two 8-bit operations
- bit 6 **T1RUN:** Timer1 System Clock Status bit
1 = Device clock is derived from Timer1 oscillator
0 = Device clock is derived from another source
- bit 5-4 **T1CKPS1:T1CKPS0:** Timer1 Input Clock Prescale Select bits
11 = 1:8 Prescale value
10 = 1:4 Prescale value
01 = 1:2 Prescale value
00 = 1:1 Prescale value
- bit 3 **T1OSCEN:** Timer1 Oscillator Enable bit
1 = Timer1 oscillator is enabled
0 = Timer1 oscillator is shut off
The oscillator inverter and feedback resistor are turned off to eliminate power drain.
- bit 2 **T1SYNC:** Timer1 External Clock Input Synchronization Select bit
When TMR1CS = 1:
1 = Do not synchronize external clock input
0 = Synchronize external clock input
When TMR1CS = 0:
This bit is ignored. Timer1 uses the internal clock when TMR1CS = 0.
- bit 1 **TMR1CS:** Timer1 Clock Source Select bit
1 = External clock from RC0/T1OSO/T13CKI pin (on the rising edge)
0 = Internal clock (Fosc/4)
- bit 0 **TMR1ON:** Timer1 On bit
1 = Enables Timer1
0 = Stops Timer1

15.0 CAPTURE/COMPARE/PWM (CCP) MODULES

PIC18F2455/2550/4455/4550 devices all have two CCP (Capture/Compare/PWM) modules. Each module contains a 16-bit register, which can operate as a 16-bit Capture register, a 16-bit Compare register or a PWM Master/Slave Duty Cycle register.

In 28-pin devices, the two standard CCP modules (CCP1 and CCP2) operate as described in this chapter. In 40/44-pin devices, CCP1 is implemented as an Enhanced CCP module, with standard Capture and Compare modes and Enhanced PWM modes. The ECCP implementation is discussed in **Section 16.0 “Enhanced Capture/Compare/PWM (ECCP) Module”**.

The Capture and Compare operations described in this chapter apply to all standard and Enhanced CCP modules.

Note: Throughout this section and **Section 16.0 “Enhanced Capture/Compare/PWM (ECCP) Module”**, references to the register and bit names for CCP modules are referred to generically by the use of ‘x’ or ‘y’ in place of the specific module number. Thus, “CCPxCON” might refer to the control register for CCP1, CCP2 or ECCP1. “CCPxCON” is used throughout these sections to refer to the module control register regardless of whether the CCP module is a standard or Enhanced implementation.

REGISTER 15-1: CCPxCON: STANDARD CCPx CONTROL REGISTER

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—(1)	—(1)	DCxB1	DCxB0	CCPxM3	CCPxM2	CCPxM1	CCPxM0
bit 7							bit 0

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as ‘0’

-n = Value at POR

‘1’ = Bit is set

‘0’ = Bit is cleared

x = Bit is unknown

bit 7-6 **Unimplemented:** Read as ‘0’⁽¹⁾

bit 5-4 **DCxB1:DCxB0:** PWM Duty Cycle Bit 1 and Bit 0 for CCPx Module

Capture mode:

Unused.

Compare mode:

Unused.

PWM mode:

These bits are the two LSBs (bit 1 and bit 0) of the 10-bit PWM duty cycle. The eight MSBs of the duty cycle are found in CCPR1L.

bit 3-0 **CCPxM3:CCPxM0:** CCPx Module Mode Select bits

0000 = Capture/Compare/PWM disabled (resets CCPx module)

0001 = Reserved

0010 = Compare mode: toggle output on match (CCPxIF bit is set)

0011 = Reserved

0100 = Capture mode: every falling edge

0101 = Capture mode: every rising edge

0110 = Capture mode: every 4th rising edge

0111 = Capture mode: every 16th rising edge

1000 = Compare mode: initialize CCPx pin low; on compare match, force CCPx pin high (CCPxIF bit is set)

1001 = Compare mode: initialize CCPx pin high; on compare match, force CCPx pin low (CCPxIF bit is set)

1010 = Compare mode: generate software interrupt on compare match (CCPxIF bit is set, CCPx pin reflects I/O state)

1011 = Compare mode: trigger special event, reset timer, start A/D conversion on CCPx match (CCPxIF bit is set)

11xx = PWM mode

Note 1: These bits are not implemented on 28-pin devices and are read as ‘0’.

PIC18F2455/2550/4455/4550

28.2 DC Characteristics: Power-Down and Supply Current PIC18F2455/2550/4455/4550 (Industrial) PIC18LF2455/2550/4455/4550 (Industrial) (Continued)

PIC18LF2455/2550/4455/4550 (Industrial)			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial						
PIC18F2455/2550/4455/4550 (Industrial)			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial						
Param No.	Symbol	Device	Typ	Max	Units	Conditions			
		Supply Current (IDD) ⁽²⁾							
		PIC18LFX455/X550	250	500	μA	-40°C	VDD = 2.0V	FOSC = 1 MHz (PRI_RUN , EC oscillator)	
			250	500	μA	+25°C			
			250	500	μA	+85°C			
		PIC18LFX455/X550	550	650	μA	-40°C	VDD = 3.0V		
			480	650	μA	+25°C			
			460	650	μA	+85°C			
		All devices	1.2	1.6	mA	-40°C	VDD = 5.0V		
			1.1	1.5	mA	+25°C			
			1.0	1.4	mA	+85°C			
		PIC18LFX455/X550	0.74	2.0	mA	-40°C	VDD = 2.0V	FOSC = 4 MHz (PRI_RUN , EC oscillator)	
			0.74	2.0	mA	+25°C			
			0.74	2.0	mA	+85°C			
		PIC18LFX455/X550	1.3	3.0	mA	-40°C	VDD = 3.0V		
			1.3	3.0	mA	+25°C			
			1.3	3.0	mA	+85°C			
		All devices	2.7	6.0	mA	-40°C	VDD = 5.0V		
			2.6	6.0	mA	+25°C			
			2.5	6.0	mA	+85°C			
		All devices	15	35	mA	-40°C	VDD = 4.2V	FOSC = 40 MHz (PRI_RUN , EC oscillator)	
			16	35	mA	+25°C			
			16	35	mA	+85°C			
		All devices	21	40	mA	-40°C	VDD = 5.0V		
			21	40	mA	+25°C			
			21	40	mA	+85°C			
		All devices	20	40	mA	-40°C	VDD = 4.2V		FOSC = 48 MHz (PRI_RUN , EC oscillator)
			20	40	mA	+25°C			
			20	40	mA	+85°C			
		All devices	25	50	mA	-40°C	VDD = 5.0V		
			25	50	mA	+25°C			
25	50		mA	+85°C					

Legend: Shading of rows is to assist in readability of the table.

- Note 1:** The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD or VSS and all features that add delta current disabled (such as WDT, Timer1 Oscillator, BOR, etc.).
- 2:** The supply current is mainly a function of operating voltage, frequency and mode. Other factors, such as I/O pin loading and switching rate, oscillator type and circuit, internal code execution pattern and temperature, also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD or VSS;
MCLR = VDD; WDT enabled/disabled as specified.
- 3:** Standard low-cost 32 kHz crystals have an operating temperature range of -10°C to +70°C. Extended temperature crystals are available at a much higher cost.
- 4:** BOR and HLVD enable internal band gap reference. With both modules enabled, current consumption will be less than the sum of both specifications.

PIC18F2455/2550/4455/4550

28.2 DC Characteristics: Power-Down and Supply Current PIC18F2455/2550/4455/4550 (Industrial) PIC18LF2455/2550/4455/4550 (Industrial) (Continued)

PIC18LF2455/2550/4455/4550 (Industrial)			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial						
PIC18F2455/2550/4455/4550 (Industrial)			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial						
Param No.	Symbol	Device	Typ	Max	Units	Conditions			
		Supply Current (IDD) ⁽²⁾							
		PIC18LFX455/X550	65	130	μA	-40°C	VDD = 2.0V	FOSC = 1 MHz (PRI_IDLE mode, EC oscillator)	
			65	120	μA	+25°C			
			70	115	μA	+85°C			
		PIC18LFX455/X550	120	270	μA	-40°C	VDD = 3.0V		
			120	250	μA	+25°C			
			130	240	μA	+85°C			
		All devices	230	480	μA	-40°C	VDD = 5.0V		
			240	450	μA	+25°C			
			250	430	μA	+85°C			
		PIC18LFX455/X550	255	475	μA	-40°C	VDD = 2.0V	FOSC = 4 MHz (PRI_IDLE mode, EC oscillator)	
			260	450	μA	+25°C			
			270	430	μA	+85°C			
		PIC18LFX455/X550	420	900	μA	-40°C	VDD = 3.0V		
			430	850	μA	+25°C			
			450	810	μA	+85°C			
		All devices	0.9	1.5	mA	-40°C	VDD = 5.0V		
			0.9	1.4	mA	+25°C			
			0.9	1.3	mA	+85°C			
		All devices	6.0	16	mA	-40°C	VDD = 4.2V	FOSC = 40 MHz (PRI_IDLE mode, EC oscillator)	
			6.2	16	mA	+25°C			
			6.6	16	mA	+85°C			
		All devices	8.1	18	mA	-40°C	VDD = 5.0V		
			8.3	18	mA	+25°C			
			9.0	18	mA	+85°C			
		All devices	8.0	18	mA	-40°C	VDD = 4.2V		FOSC = 48 MHz (PRI_IDLE mode, EC oscillator)
			8.1	18	mA	+25°C			
			8.2	18	mA	+85°C			
		All devices	9.8	21	mA	-40°C	VDD = 5.0V		
			10.0	21	mA	+25°C			
			10.5	21	mA	+85°C			

Legend: Shading of rows is to assist in readability of the table.

- Note 1:** The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to V_{DD} or V_{SS} and all features that add delta current disabled (such as WDT, Timer1 Oscillator, BOR, etc.).
- 2:** The supply current is mainly a function of operating voltage, frequency and mode. Other factors, such as I/O pin loading and switching rate, oscillator type and circuit, internal code execution pattern and temperature, also have an impact on the current consumption.
The test conditions for all I_{DD} measurements in active operation mode are:
OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to V_{DD} or V_{SS} ;
MCLR = V_{DD} ; WDT enabled/disabled as specified.
- 3:** Standard low-cost 32 kHz crystals have an operating temperature range of -10°C to $+70^{\circ}\text{C}$. Extended temperature crystals are available at a much higher cost.
- 4:** BOR and HLVD enable internal band gap reference. With both modules enabled, current consumption will be less than the sum of both specifications.

1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

$V_{DD} - V_{SS}$	7.0V
Current at Analog Input Pins (V_{IN+} , V_{IN-})	± 2 mA
Analog Inputs (V_{IN+} , V_{IN-}) ††	$V_{SS} - 1.0V$ to $V_{DD} + 1.0V$
All Other Inputs and Outputs	$V_{SS} - 0.3V$ to $V_{DD} + 0.3V$
Difference Input Voltage	$ V_{DD} - V_{SS} $
Output Short Circuit Current	Continuous
Current at Output and Supply Pins	± 30 mA
Storage Temperature	-65°C to $+150^{\circ}\text{C}$
Maximum Junction Temperature (T_J)	$+150^{\circ}\text{C}$
ESD Protection On All Pins (HBM; MM)	≥ 4 kV; 200V

† **Notice:** Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

†† See **Section 4.1.2 “Input Voltage and Current Limits”**.

DC ELECTRICAL SPECIFICATIONS

Electrical Characteristics: Unless otherwise indicated, $T_A = +25^{\circ}\text{C}$, $V_{DD} = +1.8V$ to $+5.5V$, $V_{SS} = \text{GND}$, $V_{CM} = V_{DD}/2$, $V_L = V_{DD}/2$, $R_L = 10\text{ k}\Omega$ to V_L , and $V_{OUT} \approx V_{DD}/2$ (refer to [Figure 1-1](#)).

Parameters	Sym	Min	Typ	Max	Units	Conditions
Input Offset						
Input Offset Voltage	V_{OS}	-4.5	—	+4.5	mV	$V_{CM} = V_{SS}$ (Note 1)
Input Offset Drift with Temperature	$\Delta V_{OS}/\Delta T_A$	—	± 2.0	—	$\mu\text{V}/^{\circ}\text{C}$	$T_A = -40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$, $V_{CM} = V_{SS}$
Power Supply Rejection Ratio	PSRR	—	86	—	dB	$V_{CM} = V_{SS}$
Input Bias Current and Impedance						
Input Bias Current:	I_B	—	± 1.0	—	pA	$T_A = +85^{\circ}\text{C}$ $T_A = +125^{\circ}\text{C}$
Industrial Temperature	I_B	—	19	—	pA	
Extended Temperature	I_B	—	1100	—	pA	
Input Offset Current	I_{OS}	—	± 1.0	—	pA	
Common Mode Input Impedance	Z_{CM}	—	$10^{13} 6$	—	ΩpF	
Differential Input Impedance	Z_{DIFF}	—	$10^{13} 3$	—	ΩpF	
Common Mode						
Common Mode Input Range	V_{CMR}	$V_{SS} - 0.3$	—	$V_{DD} + 0.3$	V	
Common Mode Rejection Ratio	CMRR	60	76	—	dB	$V_{CM} = -0.3V$ to $5.3V$, $V_{DD} = 5V$
Open-Loop Gain						
DC Open-Loop Gain (Large Signal)	A_{OL}	88	112	—	dB	$V_{OUT} = 0.3V$ to $V_{DD} - 0.3V$, $V_{CM} = V_{SS}$
Output						
Maximum Output Voltage Swing	V_{OL} , V_{OH}	$V_{SS} + 25$	—	$V_{DD} - 25$	mV	$V_{DD} = 5.5V$, 0.5V Input Overdrive
Output Short Circuit Current	I_{SC}	—	± 6	—	mA	$V_{DD} = 1.8V$
		—	± 23	—	mA	$V_{DD} = 5.5V$
Power Supply						
Supply Voltage	V_{DD}	1.8	—	6.0	V	Note 2
Quiescent Current per Amplifier	I_Q	50	100	170	μA	$I_O = 0$, $V_{DD} = 5.5V$, $V_{CM} = 5V$

Note 1: MCP6001/1R/1U/2/4 parts with date codes prior to December 2004 (week code 49) were tested to ± 7 mV minimum/maximum limits.

2: All parts with date codes November 2007 and later have been screened to ensure operation at $V_{DD} = 6.0V$. However, the other minimum and maximum specifications are measured at 1.8V and 5.5V.

250 mA, 16V, Low Quiescent Current LDO Regulator

Features:

- 2.0 μ A Typical Quiescent Current
- Input Operating Voltage Range: 2.7V to 16.0V
- 250 mA Output Current for Output Voltages ≥ 2.5 V
- 200 mA Output Current for Output Voltages < 2.5 V
- Low Dropout Voltage, 625 mV typical @ 250 mA for $V_R = 2.8$ V
- 0.4% Typical Output Voltage Tolerance
- Standard Output Voltage Options:
 - 1.2V, 1.5V, 1.8V, 2.5V, 2.8V, 3.0V, 3.3V, 4.0V, 5.0V
- Output Voltage Range: 1.2V to 5.5V in 0.1V Increments (50 mV increments available upon request)
- Stable with 1.0 μ F to 22 μ F Ceramic Output Capacitance
- Short-Circuit Protection
- Overtemperature Protection

Applications:

- Battery-Powered Devices
- Battery-Powered Alarm Circuits
- Smoke Detectors
- CO² Detectors
- Pagers and Cellular Phones
- Smart Battery Packs
- Low Quiescent Current Voltage Reference
- PDAs
- Digital Cameras
- Microcontroller Power
- Solar-Powered Instruments
- Consumer Products
- Battery-Powered Data Loggers

Related Literature:

- AN765, "Using Microchip's Micropower LDOs", DS00765, Microchip Technology Inc., 2002
- AN766, "Pin-Compatible CMOS Upgrades to Bipolar LDOs", DS00766, Microchip Technology Inc., 2002
- AN792, "A Method to Determine How Much Power a SOT23 Can Dissipate in an Application", DS00792, Microchip Technology Inc., 2001

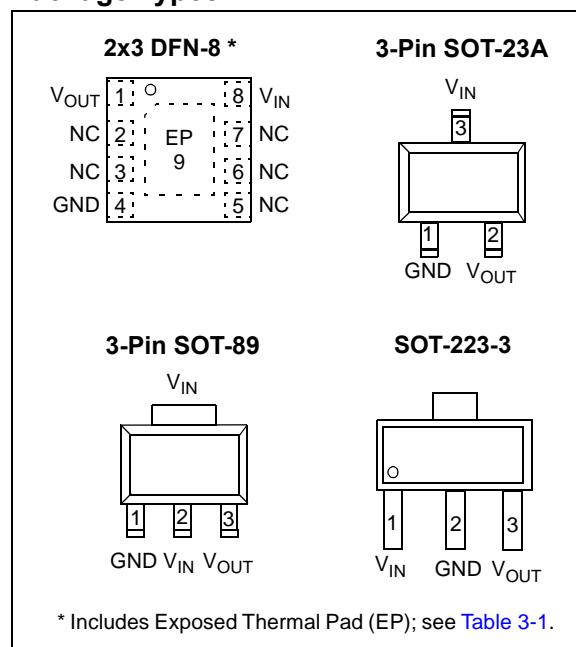
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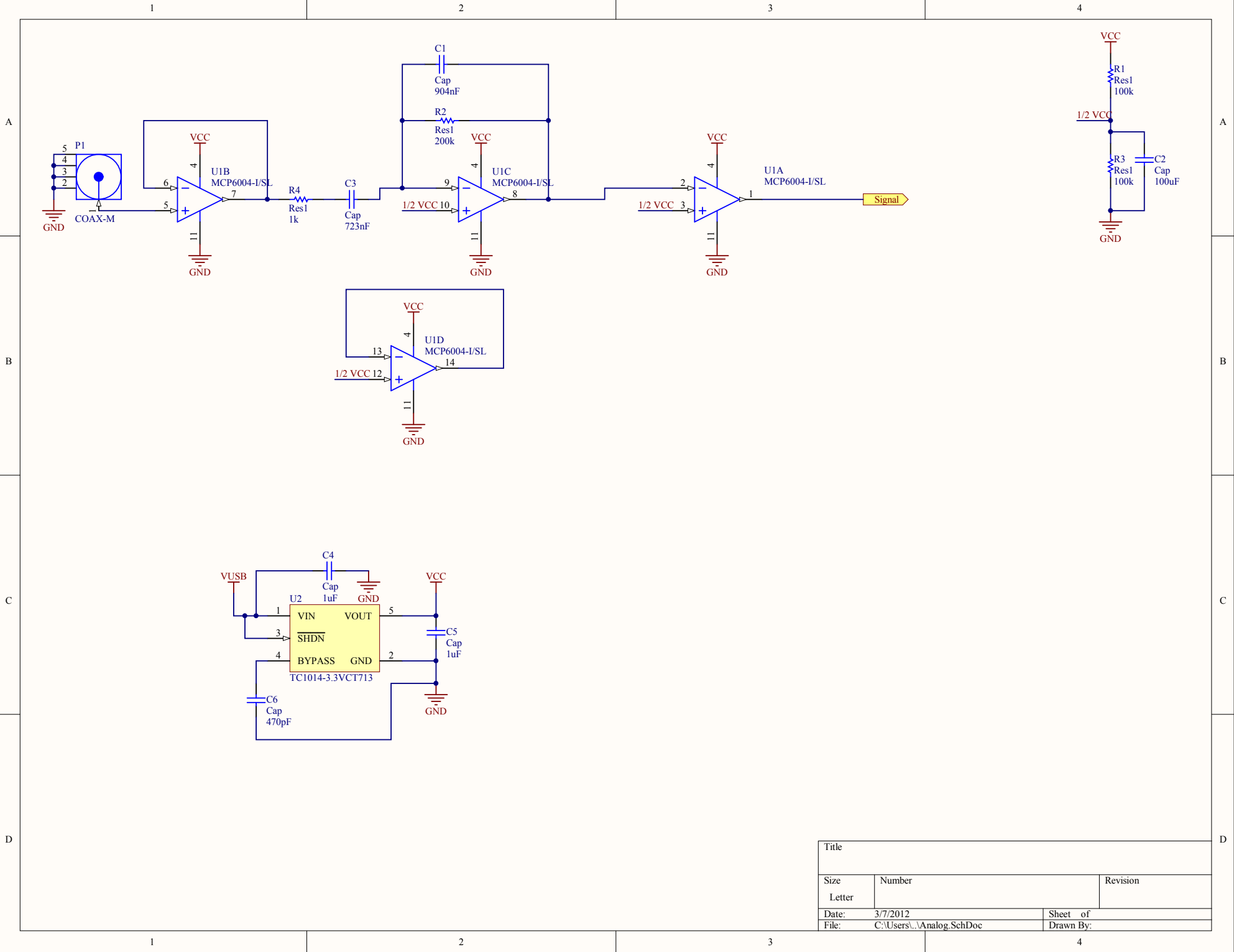
The MCP1703 is a family of CMOS low dropout (LDO) voltage regulators that can deliver up to 250 mA of current while consuming only 2.0 μ A of quiescent current (typical). The input operating range is specified from 2.7V to 16.0V, making it an ideal choice for two to six primary cell battery-powered applications, 9V alkaline and one or two cell Li-Ion-powered applications.

The MCP1703 is capable of delivering 250 mA with only 625 mV (typical) of input to output voltage differential ($V_{OUT} = 2.8$ V). The output voltage tolerance of the MCP1703 is typically $\pm 0.4\%$ at $+25^\circ\text{C}$ and $\pm 3\%$ maximum over the operating junction temperature range of -40°C to $+125^\circ\text{C}$. Line regulation is $\pm 0.1\%$ typical at $+25^\circ\text{C}$.

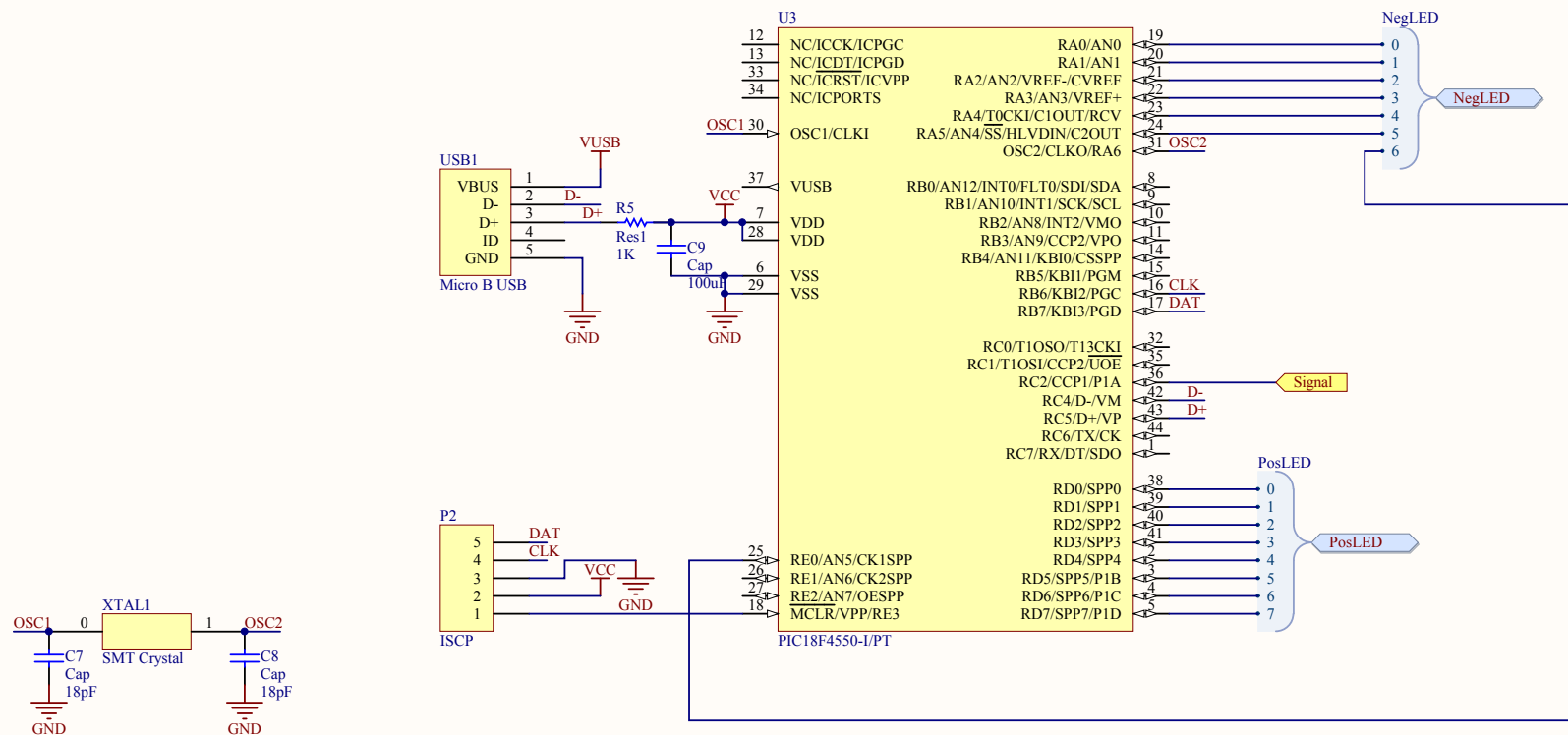
Output voltages available for the MCP1703 range from 1.2V to 5.5V. The LDO output is stable when using only 1 μ F of output capacitance. Ceramic, tantalum, or aluminum electrolytic capacitors can all be used for input and output. Overcurrent limit and overtemperature shutdown provide a robust solution for any application. Package options include the SOT-223-3, SOT-23A, 2x3 DFN-8, and SOT-89-3.

Package Types

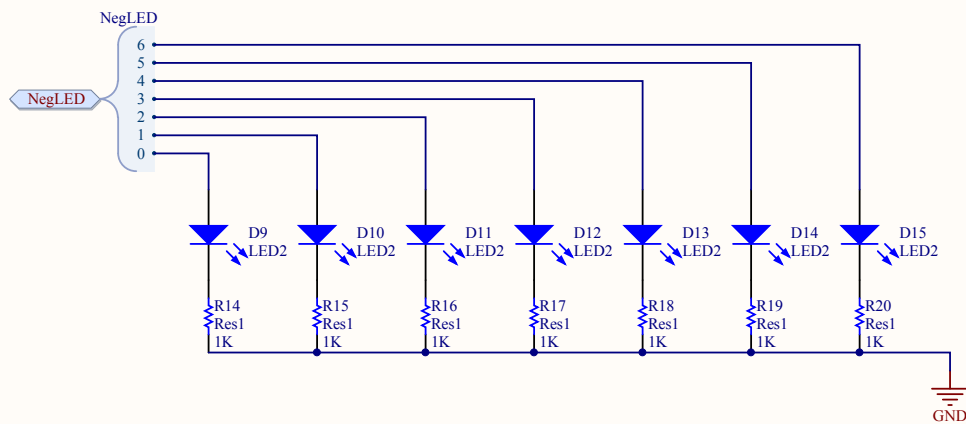
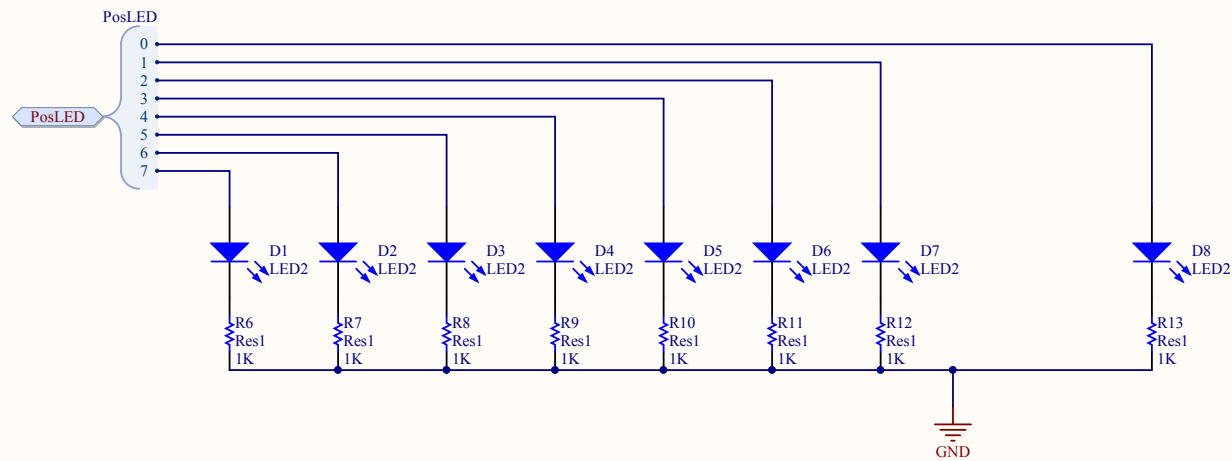




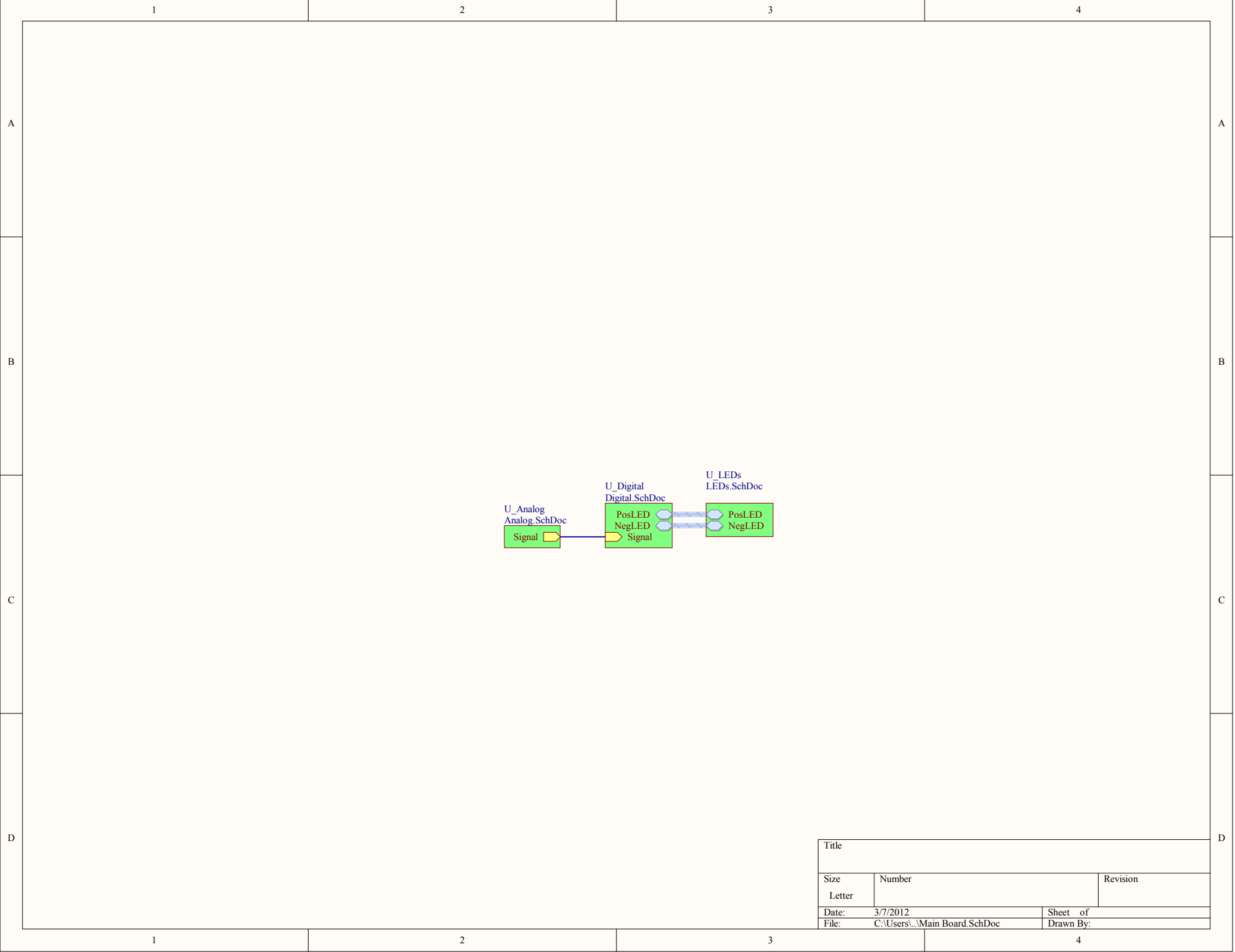
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